

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	N/A	Silicon Carbide (SiC)	409-21-2	0.01393	100.0	1.02
			<b>Subtotal</b>	<b>0.01393</b>	<b>100</b>	<b>1.02</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.04646	100.0	3.402
			<b>Subtotal</b>	<b>0.04646</b>	<b>100</b>	<b>3.402</b>
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.01989	0.03	1.4568
	Copper alloy	Iron (Fe)	7439-89-6	0.06631	0.1	4.856
	Copper alloy	Copper (Cu)	7440-50-8	66.22793	99.87	4,849.6872
			<b>Subtotal</b>	<b>66.31413</b>	<b>100</b>	<b>NaN</b>
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	1.32738	4.0	97.2
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	4.97766	15.0	364.5
	Filler	Silica fused	60676-86-0	24.55644	74.0	1,798.2
	Flame retardant	Metal hydroxide		2.32291	7.0	170.1
			<b>Subtotal</b>	<b>33.18439</b>	<b>100</b>	<b>NaN</b>
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.40968	100.0	30
			<b>Subtotal</b>	<b>0.40968</b>	<b>100</b>	<b>30</b>
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.02042	65.0	1.495
	Lead alloy	Silver (Ag)	7440-22-4	0.00785	25.0	0.575
	Lead alloy	Antimony (Sb)	7440-36-0	0.00314	10.0	0.23
			<b>Subtotal</b>	<b>0.03141</b>	<b>100</b>	<b>2.3</b>
			<b>Total</b>	<b>100</b>	<b>100</b>	<b>NaN</b>

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